

2A, 20V - 40V Surface Mount Schottky Barrier Rectifiers

FEATURES

- Very low profile typical height of 0.68mm
- Low power loss, high efficiency
- Ideal for automated placement
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21



Micro SMA







MECHANICAL DATA

Case: Micro SMA

Molding compound, UL flammability classification rating 94V-0

Moisture sensitivity level: level 1, per J-STD-020 Part no. with suffix "H" means AEC-Q101 qualified

Packing code with suffix "G" means green compound (halogen-free) **Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 2 whisker test **Polarity:** Indicated by cathode band **Weight:** 0.006 g (approximately)

PARAMETER	SYMBOL	SS22M	SS23M	SS24M	UNIT
Marking code		D	E	F	
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Maximum average forward rectified current	I _{F(AV)}	2		Α	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	25		А	
Maximum instantaneous forward voltage (Note 1) @ 2.0A / T _J =25°C @ 2.0A / T _J =125°C	V _F		0.60 0.55		V
Maximum reverse current @ rated V_R T_J =25°C T_J =125°C	I _R	150 15		μA mA	
Typical junction capacitance (Note 2)	C _J		35		pF
Typical thermal resistance	$egin{array}{c} {\sf R}_{ heta {\sf JL}} \ {\sf R}_{ heta {\sf JC}} \ {\sf R}_{ heta {\sf JA}} \end{array}$	15 20 105		°C/W	
Operating junction temperature range	T _J	-55 to +150		°C	
Storage temperature range	T _{STG}	-55 to +150			°C

Note 1: Pulse test with PW=300µs, 1% duty cycle

Note 2: Measured at 1 MHz and Applied Reverse Voltage of 4.0 V D.C.



ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
SS2xM (Note 1, 2)	Н	RS	G	Micro SMA	3,000 / 7" Plastic reel

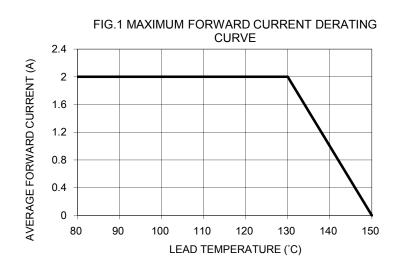
Note 1: "x" defines voltage from 20V (SS22M) to 40V (SS24M)

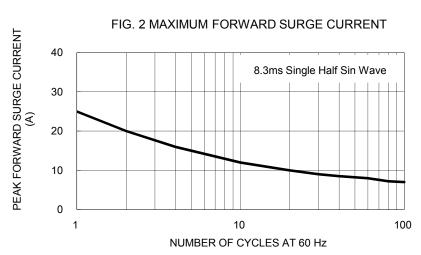
Note 2: Whole series with green compound

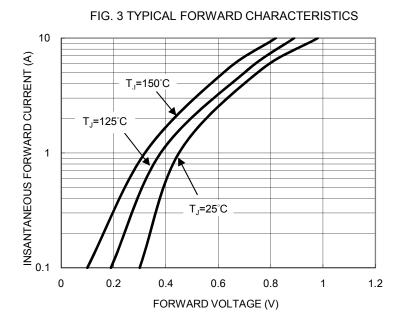
EXAMPLE					
PREFERRED PART NO.	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
SS24MHRSG	SS24M	Н	RS	G	AEC-Q101 qualified Green compound

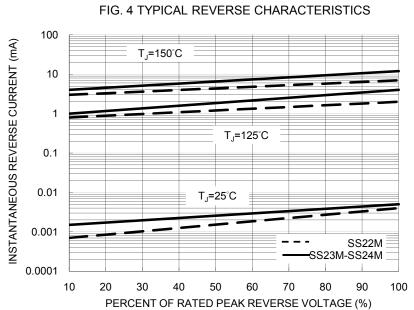
RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)









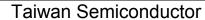




FIG. 5 TYPICAL JUNCTION CAPACITANCE

1000

(b)
100
10
10.1
1 1 10 100

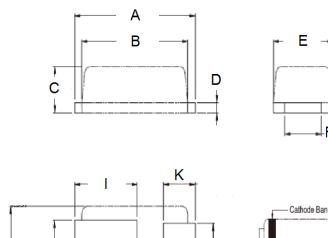
REVERSE VOLTAGE (V)

FIG. 6 TYPICAL TRANSIENT THERMAL IMPEDANCE

T-PULSE DURATION(s)

PACKAGE OUTLINE DIMENSIONS

Micro SMA

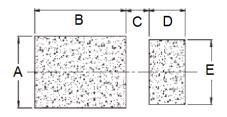


DIM.	Unit	(mm)	Unit (inch)	
DIIVI.	Min	Max	Min	Max
Α	2.30	2.70	0.091	0.106
В	2.10	2.30	0.083	0.091
С	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
Е	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	1.15	1.35	0.045	0.053
Н	0.75	0.95	0.030	0.037
I	1.10	1.50	0.043	0.059
J	0.55	0.75	0.022	0.030
K	0.55	0.75	0.022	0.030
L	0.65	0.85	0.026	0.034

SUGGESTED PAD LAYOUT

Н

G



Symbol	Unit (mm)	Unit (inch)
Α	1.1	0.043
В	2.0	0.079
С	0.5	0.020
D	0.8	0.031
E	1.0	0.039

MARKING DIAGRAM



P/N = Marking code YW = Date Code





Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

Document Number: DS_D1410055 Version: J15